

LOW CAPACITANCE BIDIRECTIONAL TVS DIODE
Product Summary

V_{BR} (MIN)	I_{PP} (MAX)	C_T (TYP)
8.5V	20A	55pF

Description

This new generation TVS is designed to protect sensitive electronics from the damage due to ESD. The combination of small size and high ESD surge capability makes it ideal for use in portable applications such as cellular phones, digital cameras, and MP3 players.

Applications

- Cellular Handsets
- Portable Electronics
- Computers and Peripheral

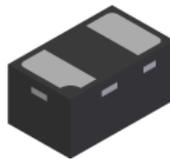
Features

- Low Profile Package (0.53mm Max) and Ultra-small PCB Footprint Area (1.08 * 0.68mm Max) Suitable for Compact Portable Electronics
- Provides ESD Protection per IEC61000-4-2 Standard: Air ±30kV, Contact ±30kV
- 1 Channel of ESD Protection
- Low Channel Input Capacitance
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.001 grams (Approximate)

X1-DFN1006-2



Bottom View

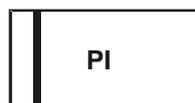


Device Schematic

Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
D8V0H1B2LP-7B	Standard	PI	7	8	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information


PI = Product Type Marking Code
Line Denotes Pin 1

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P _{PP}	350	W	8/20μs, See Figure 3
Peak Pulse Current	I _{PP}	20	A	8/20μs, See Figure 3
ESD Protection – Contact Discharge	V _{ESD_CONTACT}	±30	kV	IEC61000-4-2 Standard
ESD Protection – Air Discharge	V _{ESD_AIR}	±30	kV	IEC61000-4-2 Standard

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P _D	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V _{RWM}	—	—	8.0	V	—
Channel Leakage Current (Note 6)	I _{RM}	—	—	200	nA	V _{RWM} = 8V
Clamping Voltage, IEC61000-4-5	V _{CL}	—	—	12.0	V	I _{PP} = 1A, t _P = 8/20μs
		—	—	17.5		I _{PP} = 20A, t _P = 8/20μs
Breakdown Voltage	V _{BR}	8.5	—	12	V	I _R = 1mA
Channel Input Capacitance	C _T	—	55	—	pF	V _R = 0V, f = 1MHz

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes Incorporated's website at <http://www.diodes.com/package-outlines.html>.
6. Short duration pulse test used to minimize self-heating effect.

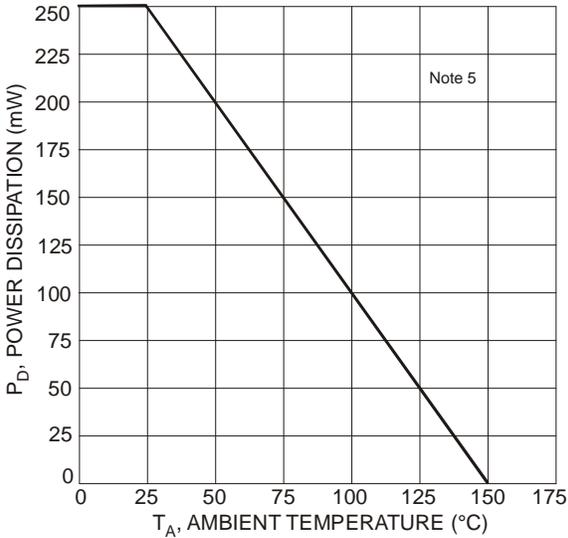


Figure 1 Power Derating Curve

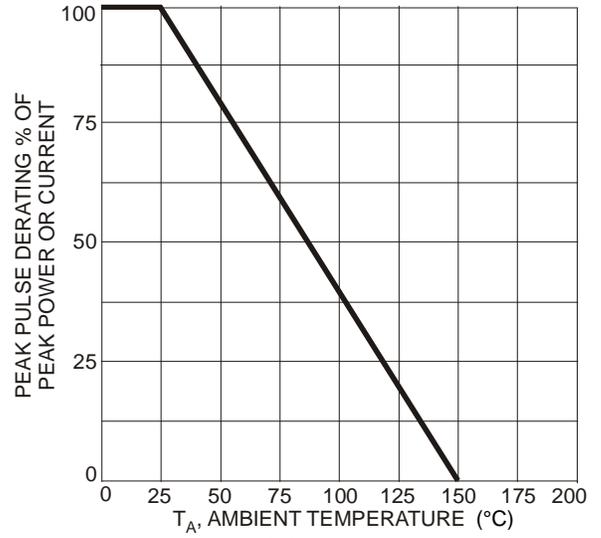


Figure 2 Pulse Derating Curve

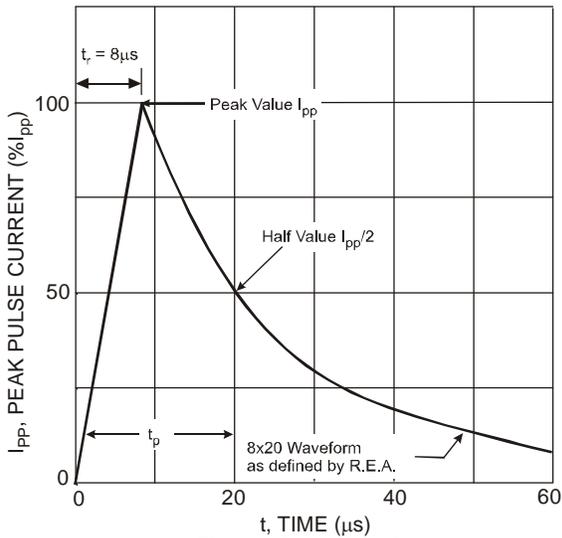


Figure 3 Pulse Waveform

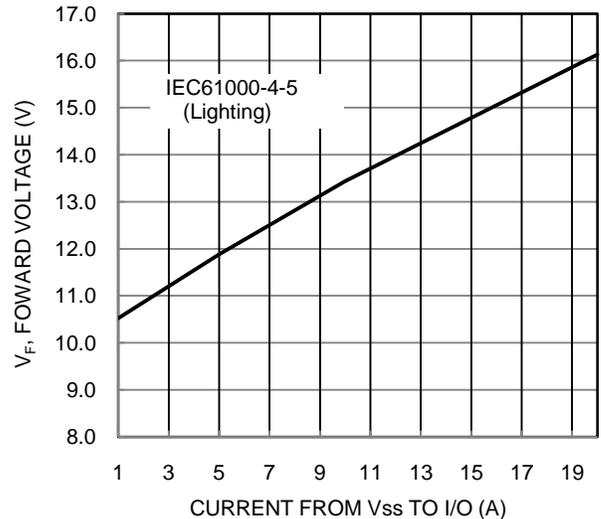


Figure 4 Forward Voltage Characteristic

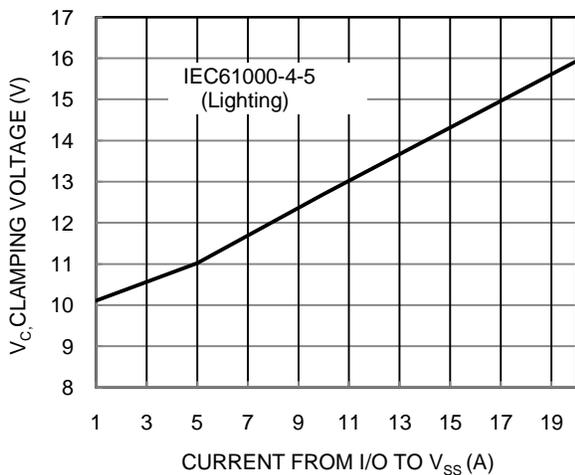


Figure 5 Clamping Voltage Characteristic

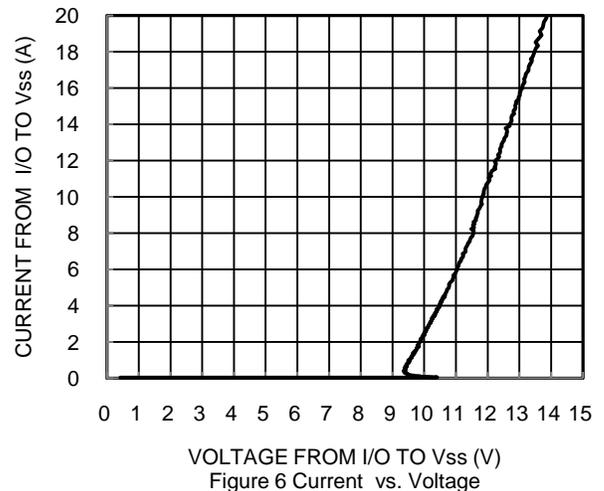
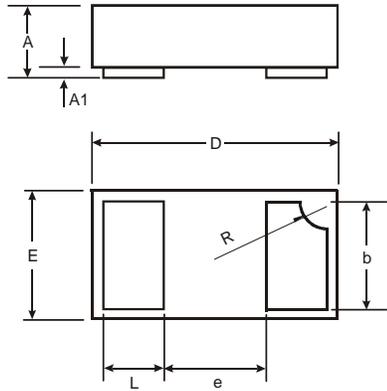


Figure 6 Current vs. Voltage

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

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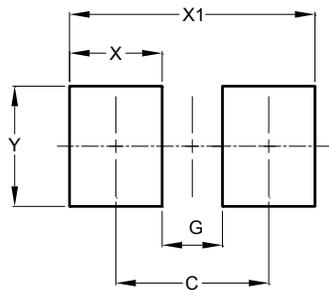


X1-DFN1006-2			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-DFN1006-2



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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